Produc Major cha	nge	s Change No	tice (PCI	N)	
Product Affect PCN Date: Effective Date Contact: Pro Phone: +49 Fax: +49	_FeCBF_2015123 cted: WE-CBF 30.12.2015 e: 01.04.2016 duct Management 0 (0) 7942 - 945 50 0 (0) 7942 - 945 51 .eisos@we-online	01 79	 Product M Date Cod Packaging Others Attachment: Samples:	е	🛛 No
In order to ir implement a	nother productio	uction capability Wür			
1. Lot N Lot r Cour Lot N Lot r Cour	production lines	iwan production line: vith 241 or 035 iwan	-	jits of the lo	ot number.
Size WE-CBF 0603	Part number74279260374279260374279260474279260674279260774279260874279261R742792622742792622R7427926247427926317427926317427926474279266R	WE-CBF 7427 0805 7427 7427	number '92012 '92034 '9207 '9207R	Size WE-CBF 1806	Part number 74279245

RELIABILITY / QUALIFICATION SUMMARY:

Process approval is according to internal requirements released by the Quality Department and the Product Management Department.

Please see the Reliability Overview as below. All Tests were passed

	Test	Qty	Reference	Test conditions	
1	High Temperature Exposure (Storage) 0/30 MIL-STD-202 Method 108			Preconditioning : 1 time lead-free Heat exposure Temperature: 125±3°C* Testing time: 500h Unpowered. Measurement at 24±2 hours after test conclusion.	
2	Moisture Resistance	0/30	MIL-STD-202 Method 106	Preconditioning : 1 time lead-free Heat exposure Time/Cycle = 24 h; Temperature: 65±2°C 500h, Humidity: 95%, Unpowered. Measurement at 24±2 hours after test conclusion.	
3	Operational Life	0/30	MIL-PRF-27	Preconditioning : 1 time lead-free Heat exposure Testing time: 1000h Temperature: Ambient Temp. 85±5°C* + rated current = 125°C* Measurement at 24±2 hours after test conclusion.	
4	Terminal Strength (SMD)	0/30	internal spec.	Preconditioning : Solder components on test board (lead-free) Apply an individual force for 60 seconds. Please refer the attached table in the description below.	
5	Vibration	0/30	MIL-STD-202 Method 204	Preconditioning : Solder components on test board (lead-free) 10g's for 20 minutes, 12 cycles each of 3 orientations. Note: Use 8"X5" PCB, .031" thick, 7 secure points on one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 15-2000 Hz.	
6	Five Time Reflow	0/30	J-STD-020D	Lead -free soldering profile: Peak temperature according to table 4.2 of the J-STD-020	
7	Solderability	0/30	JESD22-B102	For both Leaded & SMD. Electrical Test not required. Magnification 50X. Conditions: SMD: a) Method B, Steam Aging 4 hrs @ 98% r.H.@ 245°C	
8	Thermal Shock	0/30	MIL-STD-202 Method 107	Preconditioning : 1 time lead-free Heat exposure Temperature: -40°C/+125°C* Dwell time is 30 minutes. Cycles: 300 Transfer time max. 20s.	
9	Board Flex	0/30	AEC-Q200-005	Preconditioning : Solder components on test board (lead-free) Appendix 2 Note: 2mm (Min) Sample size: 30	
10	Low Temperature Storage Life	0/30	JESD22-A119	Preconditioning : 1 time lead-free Heat exposure Temperature: -55±3°C Testing time: 500h Measurement at 24±2 hours after test conclusion.	

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